



## Product Change Notification / JAON-14KDXH970

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**Date:**

19-Oct-2021

**Product Category:**

Interface- Serial Peripherals

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 2780.001 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire and A194-FH lead frame material for selected automotive MCP23S18T-E/MJVAO catalog part number (CPN) available in 24L QFN (4x4x0.9mm) package at NSEB assembly site.

**Affected CPNs:**

[JAON-14KDXH970\\_Affected\\_CPN\\_10192021.pdf](#)  
[JAON-14KDXH970\\_Affected\\_CPN\\_10192021.csv](#)

**Notification Text:**

**PCN Status:**Initial Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of palladium coated copper with gold flash (CuPdAu) bond wire and A194-FH lead frame material for selected automotive MCP23S18T-E/MJVAO catalog part number (CPN) available in 24L QFN (4x4x0.9mm) package at NSEB assembly site.

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited (UTL-1) LTD (NSEB)	UTAC Thai Limited (UTL-1) LTD (NSEB)
Wire Material	Au	CuPdAu
Die Attach Material	8600	8600
Molding Compound Material	G700LTD	G700LTD
Lead-Frame	Material	EFTEC-64T
	DAP Surface Prep	Ag Ring Ag on lead only See Pre and post change comparison

**Impacts to Data Sheet:**None

## Change ImpactNone

**Reason for Change:** To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire and A194-FH lead frame material at NSEB assembly site.

## Change Implementation Status: In Progress

**Estimated Qualification Completion Date:** December 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

## Time Table Summary:

**Method to Identify Change:**Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**October 19, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_JAON-14KDXH970\\_Pre and Post Change Summary.pdf](#)

[PCN\\_JAON-14KDXH970\\_Qual\\_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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